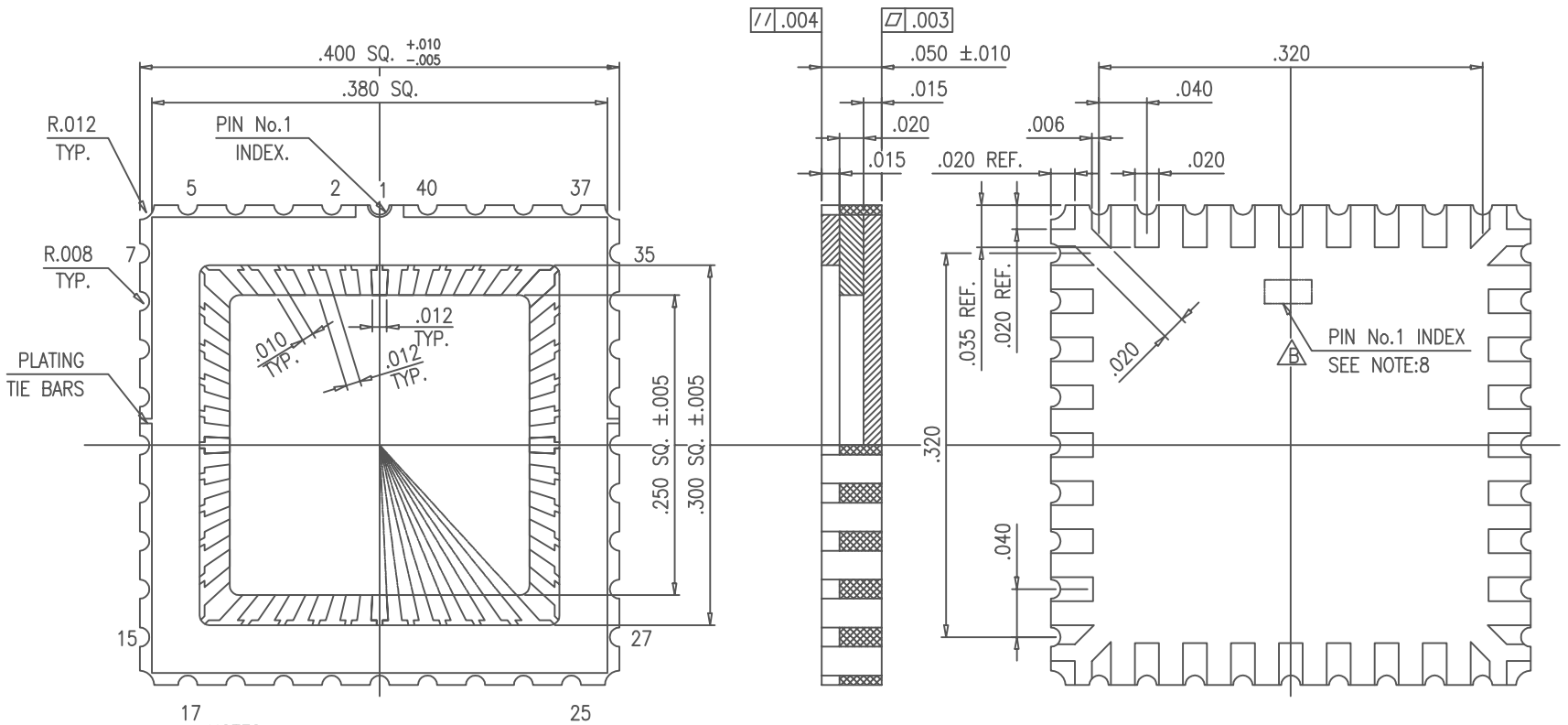

NOTES:

△A 1.

2. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCH MIN THICKNESS OVER 100 MICRO INCHES NOM THICKNESS OF NICKEL

3. FLATNESS PERTAINS TO MATALLIZED PADS ONLY.

4. LEAD TO LEAD LEAKAGE MUST NOT EXCEED 5 NANO AMPS AT 100 V DC.

5. LEAD RESISTANCE ; 0.3 Ω MAX.

6. PART OPTION
   −01− WITH SEAL RING METALLIZATION
   −02− WITHOUT SEAL RING MEATALLIZATION

7. CAPACITANCE ; 0.5PF

△C 8. INDEX MARK — △B LEAD TIED DOWN TO DIE ATTACH PAD
   ○ NO 2 ONLY
   △ NIL
   □ NO 20 ONLY

LCC04019

MODIFICATIONS					
	CHANGE	DATE	DRAWN	CHECKED	APPROVED
△C	ADDED: NOTE8 No.20 ONLY	01.24.'78	M.U	S.T	
△B	ADDED : NOTE8 TO DIE ATTACH PAD	06.09.'77	S.T		
△A	EXCEPT: NOTE1 ADDED: NOTE8	09.23.'76	S.T	E.H	S.H

NAME 40 LEAD CHIP CARRIER (DE-40C)

SCALE 10/1

MATERIAL KYOCERA A-440

TOLERANCES: UNLESS OTHERWISE SPECIFIED ±1%

N.L.T. .005

KYOCERA

KYOCERA CORPORATION
KYOTO JAPAN

	DE-40C			
DRAWN	CHECKED	APPROVED	DATE
S.M	UE / K.H	M.S	MAR.9.'99

DRAWING NO. PB-60867-C

SHEET 1/1